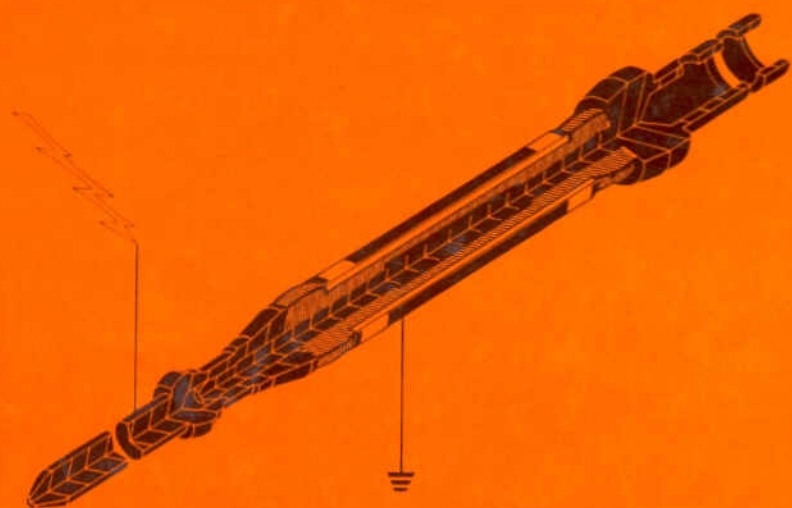


Electronic Ceramics

Properties, Devices, and Applications



edited by
Lionel M. Levinson

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Properties,
Devices,
and Applications

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General Electric Company
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